

N-Channel 60V(D-S) MOSFET

Product summary		
V_{DS}	60	V
$R_{DS(ON)}$ (at $V_{GS}=10V$) Typ.	3.9	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS}=4.5V$) Typ.	5.0	$m\Omega$
$I_D(T_c=25^\circ C)$	98	A

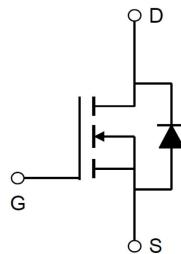
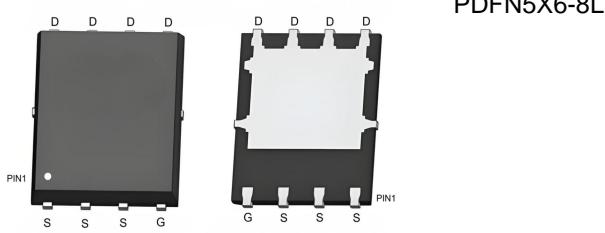
Features

- High Current Capability
- Low Gate Charge
- Ultra-low $R_{DS(ON)}$

Applications

- Power management functions
- Load switching

Pin Configuration



Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAP98N06A	PDFN5X6-8L	13"	3000pcs

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ^A	98	A
		62	A
I_{DM}	Pulse Drain Current Tested ^B	360	A
I_{AS}	Avalanche Current ^C	27	A
E_{AS}	Single Pulse Avalanche Energy ^C	109	mJ
P_D	Power Dissipation @ $T_c=25^\circ C$ ^D	78	W
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
R_{eJC}	Thermal Resistance-Junction to case max	1.6	°C/W

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^C	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	--	3.9	4.9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=15\text{A}$	--	5.0	6.3	$\text{m}\Omega$
V_{SD}	Diode Forward Voltage	$I_{\text{S}}=1\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.0	V
g_{FS}	Forward Transconductance	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=20\text{A}$	--	121	--	S
I_{S}	Diode Continuous Current	$T_C=25^\circ\text{C}$	--	--	121	A
R_{g}	Gate Resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, f=1\text{MHz}$	--	1.78	--	Ω
Dynamic Parameters ^E						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=30\text{V}$ $f=1\text{MHz}$	--	2030	--	pF
C_{oss}	Output Capacitance		--	445	--	pF
C_{rss}	Reverse Transfer Capacitance		--	4.4	--	pF
Q_{g}	Total Gate Charge (@ $V_{\text{GS}}=10\text{V}$)	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=0 \text{ to } 10\text{V}$	--	32	--	nC
Q_{g}	Total Gate Charge (@ $V_{\text{GS}}=4.5\text{V}$)		--	14.9	--	nC
Q_{gs}	Gate-Source Charge		--	4.4	--	nC
Q_{gd}	Gate-Drain Charge		--	4.9	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=30\text{V}$ $, R_{\text{GEN}}=6\Omega$, $R_L=1.5\Omega$, $V_{\text{GS}}=10\text{V}$	--	6.3	--	ns
t_r	Turn-on Rise Time		--	7.8	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	39	--	ns
t_f	Turn-off Fall Time		--	15.5	--	ns
t_{rr}	Reverse recovery time	$I_F=20\text{A}$, $di/dt=100 \text{ A/uS}$	--	39	--	ns
Q_{rr}	Reverse recovery charge		--	45	--	μC

A. Computed continuous current assumes the condition of T_J_{Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.

B. This single-pulse measurement was taken under $T_J_{\text{Max}}=150^\circ\text{C}$.

C. This single-pulse measurement was taken under the following condition [$L=300\mu\text{H}$, $V_{\text{GS}}=10\text{V}$, $V_{\text{DS}}=30\text{V}$] while its value is limited by $T_J_{\text{Max}}=150^\circ\text{C}$.

D. The power dissipation PD is based on $T_J_{\text{Max}}=150^\circ\text{C}$.

E. Guaranteed by design, not subject to production testing.

F. Continuous current rating is limited by the package used.

Typical Characteristics

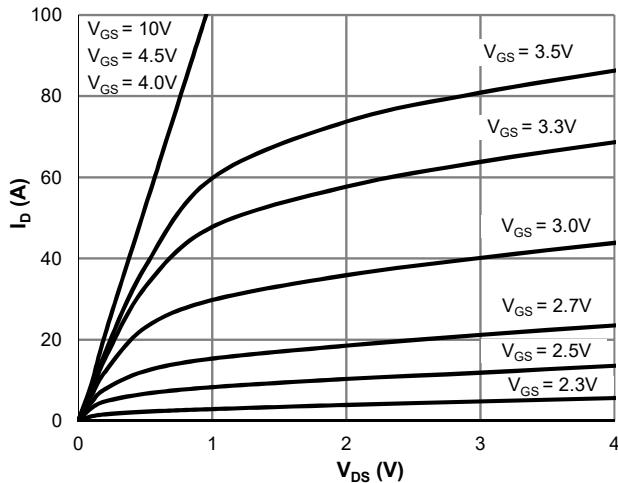


Figure 1: Saturation Characteristics

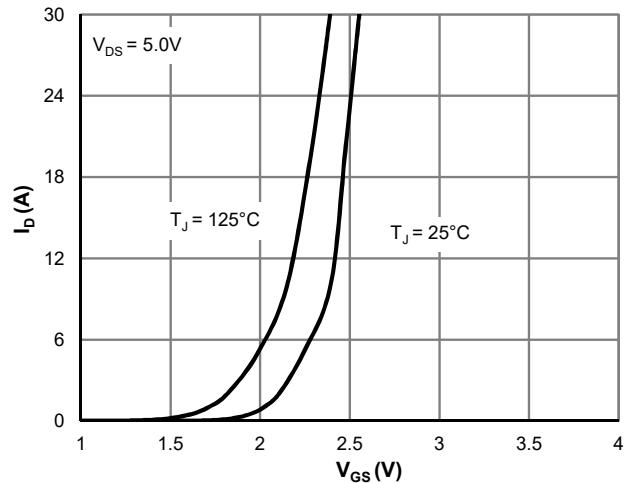


Figure 2: Transfer Characteristics

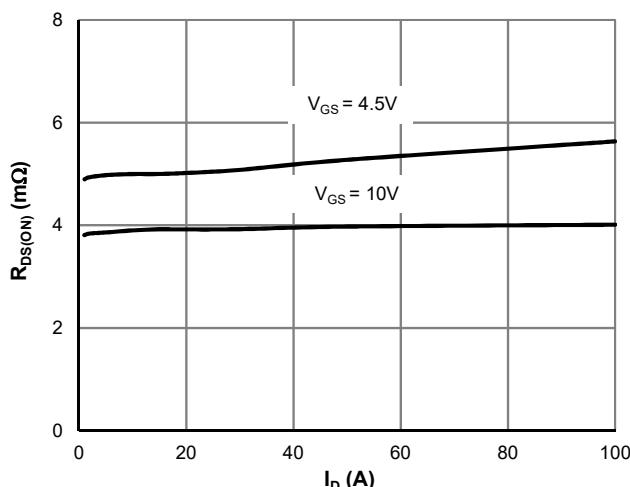


Figure 3: $R_{DS(ON)}$ vs. Drain Current

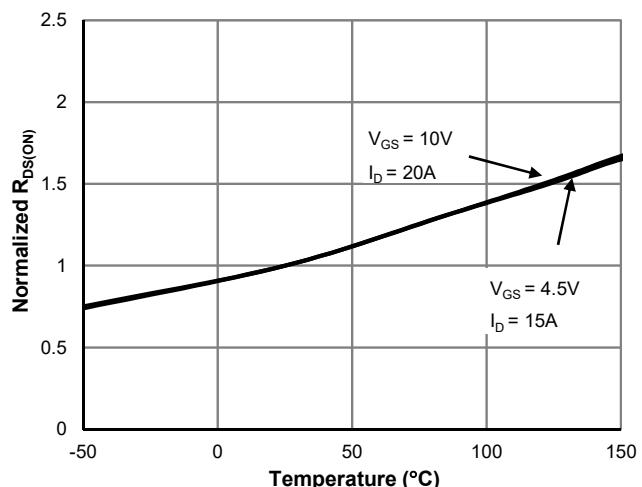


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

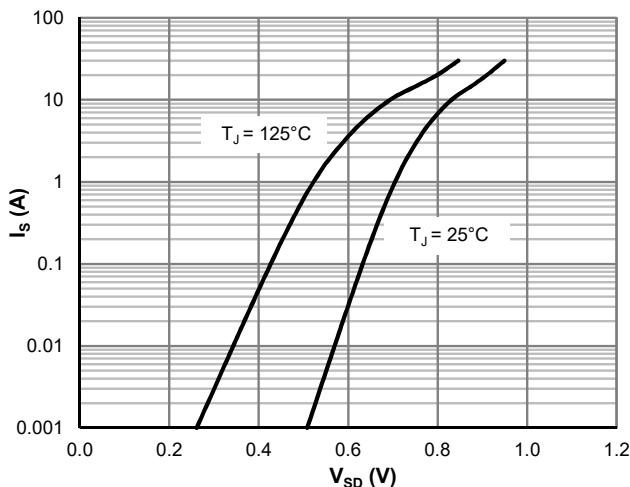


Figure 5: Body-Diode Characteristics

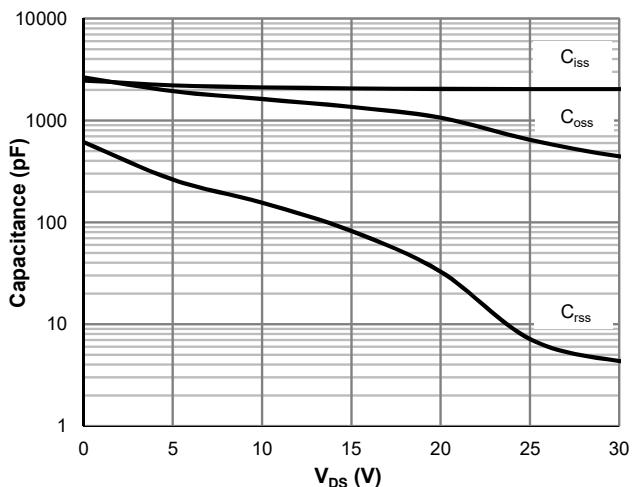


Figure 6: Capacitance Characteristics

Typical Characteristics

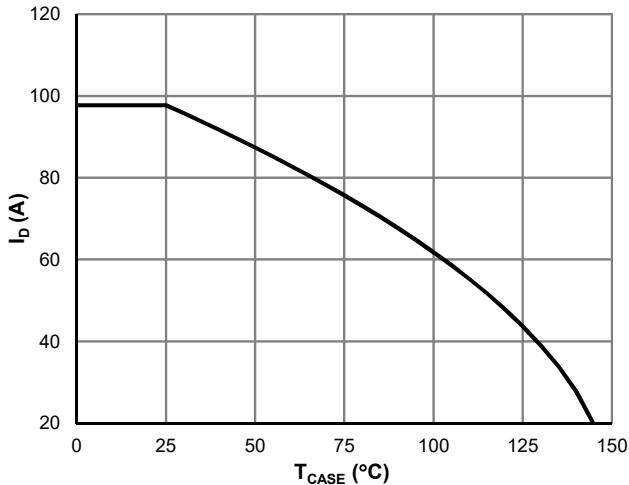


Figure 7: Current De-rating

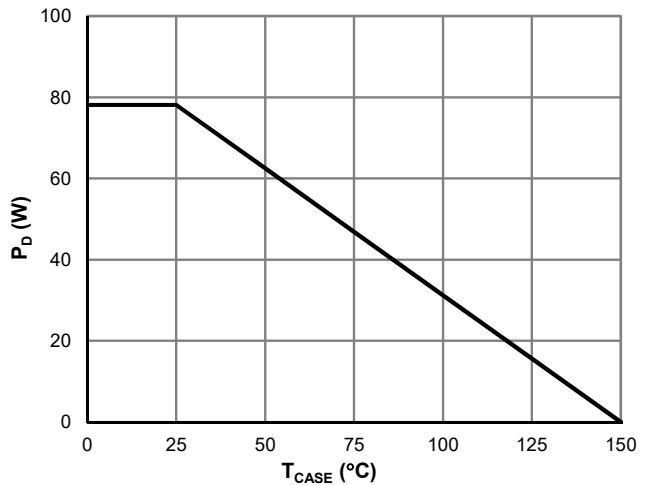


Figure 8: Power De-rating

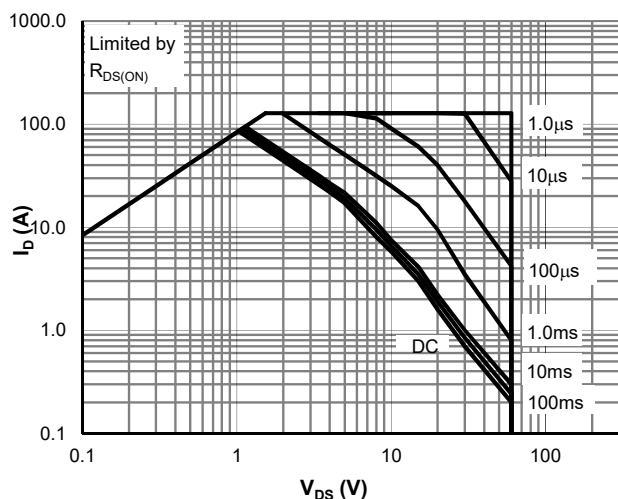


Figure 9: Maximum Safe Operating Area

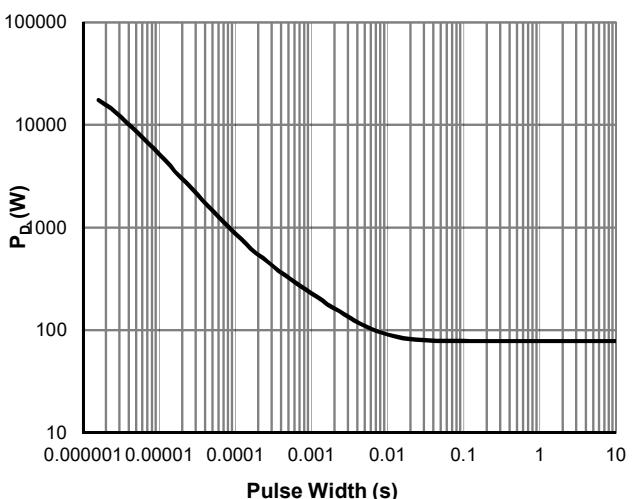


Figure 10: Single Pulse Power Rating, Junction-to-Case

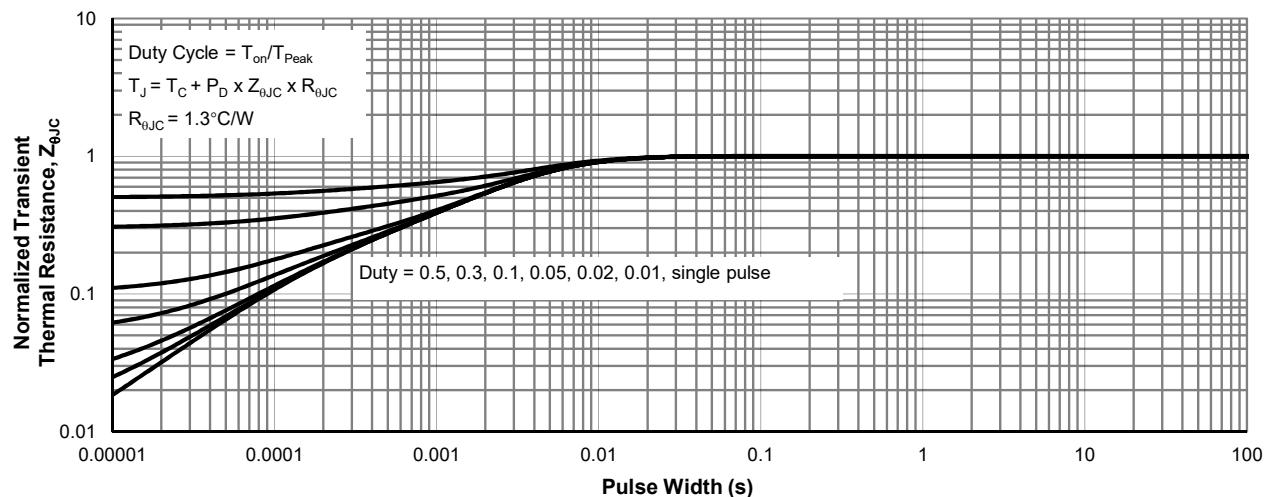
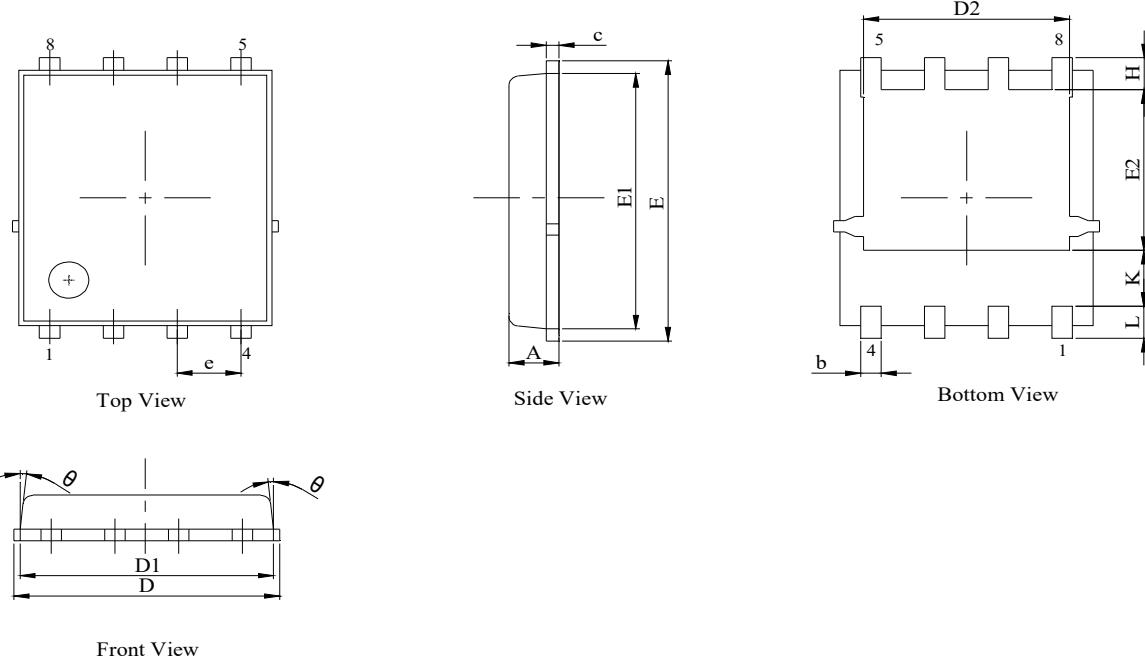


Figure 11: Normalized Maximum Transient Thermal Impedance

PDFN5X6-8L Package Information (unit:mm)



NOTES:

1. Dimension and tolerance per ASME Y14.5M, 1994.
2. All dimensions in millimeter (angle in degree).
3. Dimensions D1 and E1 do not include mold flash protrusions or gate burrs.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	0.31	0.41	0.51
c	0.20	0.25	0.30
D	5.00	5.20	5.40
D1	4.95	5.05	5.15
D2	4.00	4.10	4.20
E	6.05	6.15	6.25
E1	5.50	5.60	5.70
E2	3.42	3.53	3.63
e	1.27BSC		
H	0.60	0.70	0.80
L	0.50	0.70	0.80
θ	-	-	10°